

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

SAMSUNG ELECTRONICS COMPANY, LTD.
Petitioner

v.

DANIEL L. FLAMM
Patent Owner

U.S. Patent No. 5,711,849

**PETITION FOR *INTER PARTES* REVIEW
OF U.S. PATENT NO. 5,711,849**

TABLE OF CONTENTS

	Page
1. INTRODUCTION	1
2. REQUIREMENTS FOR PETITION FOR INTER PARTES REVIEW	1
2.1 Grounds for Standing (37 C.F.R. § 42.104(a))	1
2.2 Notice of Lead and Backup Counsel and Service Information.....	2
2.3 Notice of Real-Parties-in-Interest (37 C.F.R. § 42.8(b)(1)).....	3
2.4 Notice of Related Matters (37 C.F.R. § 42.8(b)(2)).....	3
2.5 Fee for <i>Inter Partes</i> Review	5
2.6 Proof of Service.....	5
3. IDENTIFICATION OF CLAIMS BEING CHALLENGED (§ 42.104(B)).....	5
4. OVERVIEW OF THE 849 PATENT.....	5
5. 849 PATENT PROSECUTION HISTORY	13
6. CLAIM CONSTRUCTION	15
6.1 Applicable Law	15
6.2 Construction of Claim Terms.....	15
6.2.1 “surface reaction rate constant” (all claims).....	16
7. PERSON HAVING ORDINARY SKILL IN THE ART	19
8. DESCRIPTION OF THE PRIOR ART	20
8.1 Alkire (Ex. 1005).....	20
8.2 Galewski (Ex. 1007).....	24
8.3 Motivations To Combine: Alkire in Combination with Galewski.....	28
9. GROUND #1: CLAIMS 1-29 OF THE 849 PATENT ARE UNPATENTABLE AS OBVIOUS OVER ALKIRE IN VIEW OF GALEWSKI	31
9.1 Claim 1 is obvious over Alkire in view of Galewski.....	31
9.1.1 [1.P] “A device fabrication method comprising the steps of:”	31

9.1.2	[1.1] “providing a plasma etching apparatus comprising a substrate therein, said substrate comprising a top surface and a film overlying said top surface, said film comprising a top film surface;”	32
9.1.3	[1.2] “etching said top film surface to define a relatively non-uniform etching profile on said film, and defining etch rate data comprising an etch rate and a spatial coordinate which defines a position within said relatively non-uniform etching profile on said substrate, said etching comprising a reaction between a gas phase etchant and said film; and”	34
9.1.4	[1.3] “extracting a surface reaction rate constant from said etch rate data, and using said surface reaction rate constant in the fabrication of a device.”	38
9.2	Claim 10 is obvious over Alkire in view of Galewski	45
9.2.1	[10.P] “A method of designing a reactor comprising the steps of:”	45
9.2.2	[10.1] “providing a first plasma etching apparatus comprising a substrate therein, said substrate comprising a top surface and a film overlying said top surface, said film comprising a top film surface”	46
9.2.3	[10.2] “etching said top film surface to define a relatively non-uniform etching profile on said film, and defining etch rate data comprising an etch rate and a spatial coordinate which defines a position within said relatively non-uniform etching profile on said film of said substrate, said etching comprising a reaction between a gas phase etchant and said film; and”	47
9.2.4	[10.3] “extracting a surface reaction rate constant from said etch rate data, and using said surface reaction rate constant in designing a second plasma etching apparatus.”	47
9.3	Claim 20 is obvious over Alkire in view of Galewski	48
9.3.1	[20.P] “A substrate fabrication method, using a plasma etching apparatus, said method comprising:”	48

9.3.2	[20.1] “providing a substrate selected from a group consisting of a semiconductor wafer, a plate, and a flat panel display, said substrate comprising a top surface;”	48
9.3.3	[20.2] “forming a film overlying said top surface, said film comprising a top film surface;”	49
9.3.4	[20.3] “etching said top film surface to define a relatively non-uniform profile on said film, and defining etch rate data comprising an etch rate and a spatial coordinate which defines a position within said relatively non-uniform etching profile of said film on said substrate, said etching comprising a reaction between a gas phase etchant and said film; and”	50
9.3.5	[20.4] “extracting a surface reaction rate constant from said etch rate data, and using said surface reaction rate constant.”	50
9.4	Claim 22 is obvious over Alkire in view of Galewski	50
9.4.1	[22.P] “A method of fabricating an integrated circuit device, using a plasma etching apparatus, said method comprising:”	50
9.4.2	[22.1] “providing a uniformity value and a surface reaction rate constant for an etching reaction, said etching reaction including a substrate and etchant species;”	51
9.4.3	[22.2] “defining etching parameters providing said uniformity value; and”	52
9.4.4	[22.3] “adjusting at least one of said etching parameters using said surface reaction rate constant to produce a selected etching rate”	53
9.4.5	[22.4] “wherein said etching rate providing an etching condition for fabrication of an integrated circuit device.”	55
9.5	Claim 26 is obvious over Alkire in view of Galewski	56
9.5.1	[26.P] “A process for fabricating a device using a plasma etching apparatus, said device being fabricated by use of a surface reaction rate constant, said surface reaction rate constant being derived from a method comprising:”	56

9.5.2	[26.1] “providing a plasma etching apparatus comprising a substrate therein, said substrate comprising a top surface and a film overlying said top surface, said film comprising a top film surface”	57
9.5.3	[26.2] “etching said top surface at a temperature to define a relatively non-uniform etching profile on said film, and defining etch rate data comprising an etch rate and a spatial coordinate which defined a position from said relatively non-uniform etching profile on said film of said substrate, said etching comprising a reaction between a gas phase etchant and said film; and”	57
9.5.4	[26.3] “extracting from said etching rate data a surface reaction rate constant for said temperature.”	58
9.6	Dependent Claims 2 and 11 are obvious over Alkire in view of Galewski	58
9.6.1	[2.0] “The method of claim 1 wherein said etching step is diffusion limited.”	58
9.7	Dependent Claims 3 and 12 are obvious over Alkire in view of Galewski	59
9.7.1	[3.0] “The method of claim 1 wherein said spatial coordinate includes a radius and an angle.”	59
9.8	Dependent Claims 4 and 13 are obvious over Alkire in view of Galewski	62
9.8.1	[4.0] “The method of claim 1 wherein said spatial coordinate includes an x-direction and a y-direction.”	62
9.9	Dependent Claims 5 and 14 are obvious over Alkire in view of Galewski	63
9.9.1	[5.0] “The method of claim 1 wherein said extracting step correlates said surface reaction rate constant over a diffusivity with said etch rate, said etch rate being defined by said relatively non-uniform etching profile.”	63
9.10	Dependent Claims 6 and 15 are obvious over Alkire in view of Galewski	64

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